TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (High speed U-MOSIII)

# ТРС8010-Н

DC-DC Converters Notebook PC Applications Portable Equipment Applications

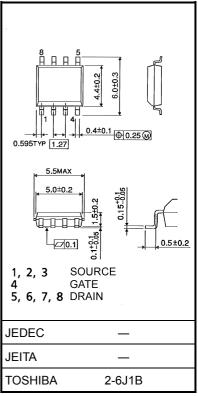
- Small footprint due to small and thin package
- High speed switching
- Small gate charge:  $Q_g = 18 \text{ nC}$  (typ.)
- Low drain-source ON resistance:  $R_{DS}$  (ON) = 12 m $\Omega$  (typ.)
- High forward transfer admittance:  $|Y_{fs}| = 11 \text{ S} (typ.)$
- Low leakage current:  $I_{DSS} = 10 \ \mu A \ (max) \ (V_{DS} = 30 \ V)$
- Enhancement mode:  $V_{th}$  = 1.1 to 2.3 V (V\_{DS} = 10 V,  $I_{D}$  = 1 mA)

#### Maximum Ratings (Ta = 25°C)

Characte	ristics	Symbol	Rating	Unit	
Drain-source voltage		V <sub>DSS</sub>	30	V	
Drain-gate voltage (R	$R_{\rm GS} = 20 \ \rm k\Omega$ )	V <sub>DGR</sub>	30	V	
Gate-source voltage		V <sub>GSS</sub>	±20	V	
Drain current	DC (Note 1)	Ι <sub>D</sub>	11	Α	
Drain current	Pulse (Note 1)	I <sub>DP</sub>	44	~	
Drain power dissipati	on (t = 10 s) (Note 2a)	PD	1.9	W	
Drain power dissipati	on (t = 10 s) (Note 2b)	PD	1.0	W	
Single pulse avalancl	ne energy (Note 3)	E <sub>AS</sub>	157	mJ	
Avalanche current		I <sub>AR</sub>	11	A	
Repetitive avalanche (	energy Note 2a) (Note 4)	E <sub>AR</sub>	0.19	mJ	
Channel temperature		T <sub>ch</sub>	150	°C	
Storage temperature	range	T <sub>stg</sub>	-55 to 150	°C	

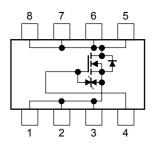
Note: For (Note 1), (Note 2), (Note 3) and (Note 4), please refer to the next page.

This transistor is an electrostatic sensitive device. Please handle with caution.



Weight: 0.080 g (typ.)

#### **Circuit Configuration**



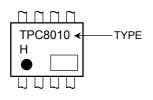
Unit: mm

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### **Thermal Characteristics**

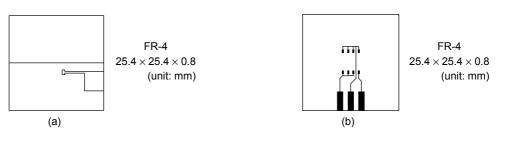
Characteristics	Symbol	Max	Unit
Thermal resistance, channel to ambient (t = 10 s) (Note 2a)	R <sub>th (ch-a)</sub>	65.8	°C/W
Thermal resistance, channel to ambient (t = 10 s) (Note 2b)	R <sub>th (ch-a)</sub>	125	°C/W

## Marking (Note 5)



Note 1: Please use devices on condition that the channel temperature is below  $150^{\circ}C$ .

Note 2: (a) Device mounted on a glass-epoxy board (a)



(b) Device mounted on a glass-epoxy board (b)

- Note 3:  $V_{DD} = 24 \text{ V}, \text{ T}_{ch} = 25^{\circ}\text{C}$  (initial), L = 1.0 mH, R<sub>G</sub> = 25  $\Omega$ , I<sub>AR</sub> = 11 A
- Note 4: Repetitive rating: pulse width limited by maximum channel temperature
- Note 5: on lower left of the marking indicates Pin 1.

shows lot number. (year of manufacture: last decimal digit of the year of manufacture, month of manufacture: January to December are denoted by letters A to L respectively.)

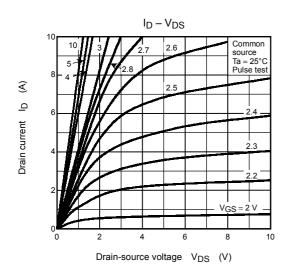
Electrical Characteristics (Ta = 25°C)

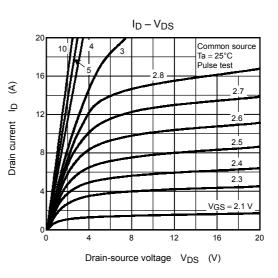
Ch	Characteristics S		Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	rrent	I <sub>GSS</sub>	$V_{GS}=\pm 16~V,~V_{DS}=0~V$	_		±10	μA
Drain cut-OFF cu	urrent	I <sub>DSS</sub>	$V_{DS} = 30 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$	_	_	10	μA
Drain-source bre	akage current tt-OFF current  purce breakdown voltage eshold voltage purce ON resistance transfer admittance pacitance transfer capacitance apacitance transfer capacitance apacitance fall time Turn-OFF time te charge urce plus gate-drain)	V (BR) DSS	$I_{D} = 10 \text{ mA}, V_{GS} = 0 \text{ V}$	30	—	—	v
		V (BR) DSX	$I_D = 10 \text{ mA}, V_{GS} = -20 \text{ V}$	15	$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	v	
Gate threshold v	oltage	V <sub>th</sub>	$V_{DS} = 10 \text{ V}, \text{ I}_{D} = 1 \text{ mA}$	1.1	—	2.3	V
		Proven	$V_{GS} = 4.5 \text{ V}, \text{ I}_{D} = 5.5 \text{ A}$	_	16	25	- mΩ
Diam-source ON	resistance	NDS (ON)	$V_{GS} = 10 \text{ V}, \text{ I}_{D} = 5.5 \text{ A}$	$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	16		
Forward transfer	admittance	Y <sub>fs</sub>	$V_{DS} = 10 \text{ V}, \text{ I}_{D} = 5.5 \text{ A}$	5.5	11		S
Input capacitance	nput capacitance		$V_{DS} = 10 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ f} = 1 \text{ MHz}$	_	1020		pF
Reverse transfer capacitance		C <sub>rss</sub>			120		
Output capacitance		C <sub>oss</sub>			400		
	Rise time	t <sub>r</sub>	10 V 🗖 lp = 5.5 A	_	3.1	_	
Qualitaching a time o	$ \frac{1}{\text{DSS}}  V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V} \qquad$	11					
Switching time	Fall time	t <sub>f</sub>	R = 2:		3.4		- ns
	Turn-OFF time	t <sub>off</sub>	55		23		
Total gate charge	ate charge		$V_{DD}\simeq 24~V,~V_{GS}=10~V,~I_{D}=11~A$	_	18		
(gate-source plus	s gate-drain)	μg	$V_{DD}\simeq 24~V,~V_{GS}=5~V,~I_{D}=11~A$		10		
Gate-source charge 1		Q <sub>gs1</sub>			2.6		nC
Gate-drain ("miller") charge		Q <sub>gd</sub>	$V_{DD}\simeq 24~V,~V_{GS}=10~V,~I_{D}=11~A$	_	4.4	—	1
Gate switch char	ge	Q <sub>SW</sub>		_	5.5		1

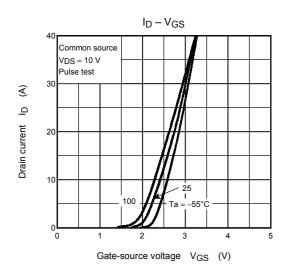
## Source-Drain Ratings and Characteristics (Ta = 25°C)

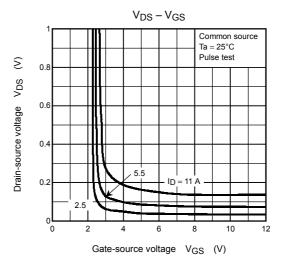
Characteri	Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit
Drain reverse current	Pulse	(Note 1)	I <sub>DRP</sub>	—	_	_	44	А
Forward voltage (diode)			V <sub>DSF</sub>	I <sub>DR</sub> = 11 A, V <sub>GS</sub> = 0 V	_	_	-1.2	V

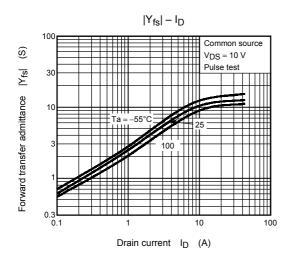
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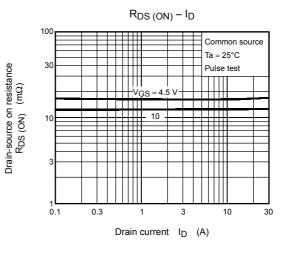




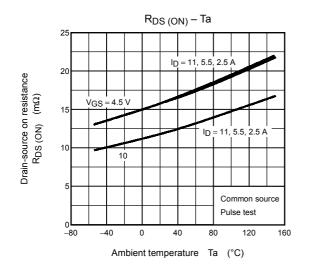


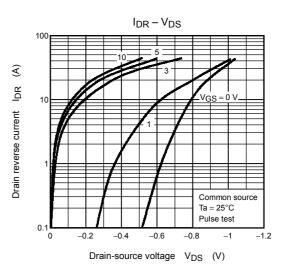


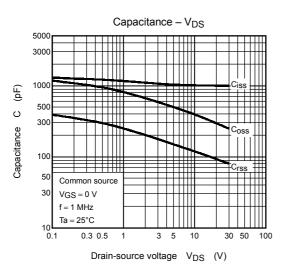


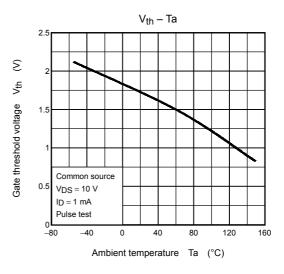


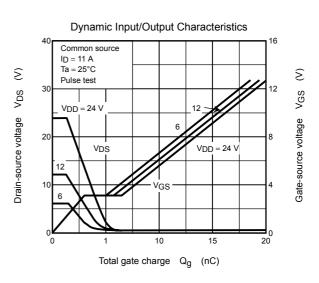
# **TOSHIBA**

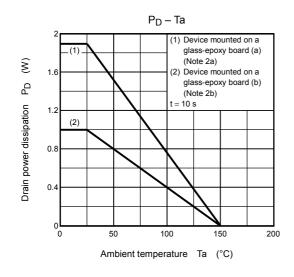


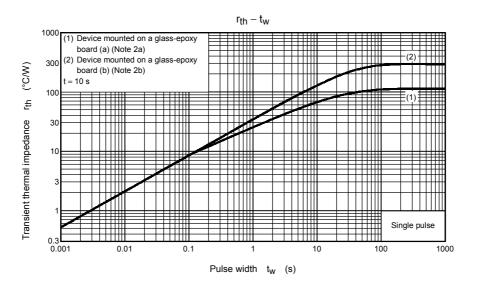




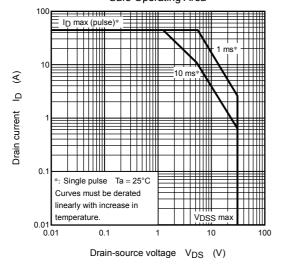








Safe Operating Area



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